PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4257453

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
NXP B.V.	02/02/2017

RECEIVING PARTY DATA

Name:	NEXPERIA B.V.
Street Address:	HIGH TECH CAMPUS 60
City:	EINDHOVEN
State/Country:	NETHERLANDS
Postal Code:	5656 AG

PROPERTY NUMBERS Total: 8

Property Type	Number
Application Number:	15343172
Application Number:	15357570
Application Number:	15355769
Application Number:	15344564
Application Number:	15371219
Application Number:	15379495
Application Number:	15382805
Application Number:	29588103

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 408-518-5500
Email: vilimaina.naga@nxp.com
Correspondent Name: INTELLECTUAL PROPERTY AND LICENSING NXP
Address Line 1: 411 EAST PLUMERIA DRIVE, MS41
Address Line 4: SAN JOSE, CALIFORNIA 95134

NAME OF SUBMITTER:	VILIMAINA NAGA
SIGNATURE:	/Vilimaina Naga/
DATE SIGNED:	02/02/2017

Total Attachments: 5
source=NXP B.V. TO NEXPERIA 2-2-2016#page1.tif
source=NXP B.V. TO NEXPERIA 2-2-2016#page2.tif
source=NXP B.V. TO NEXPERIA 2-2-2016#page3.tif
source=NXP B.V. TO NEXPERIA 2-2-2016#page4.tif
source=NXP B.V. TO NEXPERIA 2-2-2016#page5.tif

DEED OF TRANSFER OF THE LEGAL TITLE TO CERTAIN PATENTS

THIS AGREEMENT IS MADE BETWEEN: THE UNDERSIGNED:

(1) NXP B.V., residing at High Tech Campus 60, 5656 AG Eindhoven, the Netherlands, a Dutch entity, with seat in Eindhoven, the Netherlands, Trade Register number 17070622 (the "**Seller**");

and

(2) Nexperia B.V., residing at High Tech Campus 60, 5656 AG Eindhoven, the Netherlands, a Dutch entity, with seat in Nijmegen, the Netherlands, Trade Register number 66264111 (the "**Company**");

together also to be referred to as "**Parties**" and each party individually as a "**Party**", as the case may be,

BACKGROUND:

(A) The Parties hereby wish to transfer the legal title to the Transferred Patents to the Company on the terms and conditions as set out in this Deed.

THE PARTIES AGREE AS FOLLOWS:

1 **DEFINITIONS**

Any capitalized term used in this Deed but not defined will have the same meaning as ascribed to it in the IPSPA or the IPTLA.

2 **TRANSFER OF LEGAL OWNERSHIP OF THE TRANSFERRED IP**

By this Deed, the Seller assigns, transfers, conveys and delivers to the Company its legal title to the Transferred Patents, including the right to sue and claim

damages or any other remedies for any act of infringement prior to the Effective Date, and for the avoidance of doubt, the right to claim priority relating to any of the Transferred Patents, and the Company hereby accepts from Seller such assignment, transfer, conveyance and delivery. Seller authorizes and requests the relevant national or international Patent Office, or any other Office for Intellectual Property worldwide to record the Company as the owner of the Transferred Patents in the relevant patent register.

3 VARIATION TO THE DEED

No variation, extension, cancellation or translation of any expressed terms of this Deed (including in Schedule 1) will be binding upon Seller or the Company unless made in writing and signed by duly authorized representatives of Seller and the Company.

4 ADDITIONAL ASSIGNMENT DOCUMENTS; FURTHER ASSURANCE

The Seller will be responsible for effectuating the registration of the assignment and transfer of the Transferred Patents. Seller and the Company shall, at each other's request, execute and do all such deeds, documents, acts and things as the requesting Party may from time to time reasonably require in order to effectuate or formalize the transfer of the Transferred Patents to the Company and to cause the Transferred Patents to be recorded at the relevant patent registers around the world in the name of the Company.

5 OBSERVANCE OF LEGAL REQUIREMENTS

The Company and Seller undertake to observe and act in accordance with all applicable legal conditions and terms required in order to effectuate the registration of the assignment and transfer of the Transferred Patents in the relevant registers.

6 COSTS FOR REGISTRATION

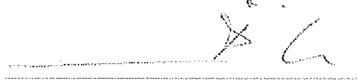
Without prejudice to Clause 8.4 of the IPTLA, the costs for the registration of the assignment and transfer of the Transferred IP in the relevant registers will be borne by the Seller.

7 APPLICABLE LAW AND JURISDICTION

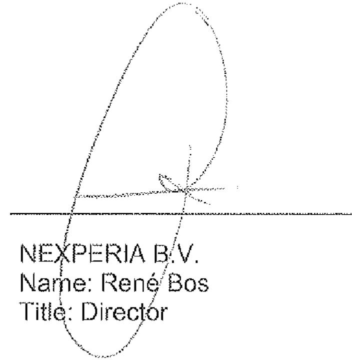
This Deed will be governed by and construed in accordance with the laws of the Netherlands. Any action or proceeding in respect of any claim arising out of or related to this Deed will be conducted by Seller and the Company in accordance with the dispute settlement procedure provided in the IPSPA.

8 NO RESCISSION AND NO NULLIFICATION

Each Party hereby waives its right to rescind *(ontbinden)* this Deed on the basis of Section 6:265 of the Dutch Civil Code.



NXP B.V.
Name: Guido Dierick
Title: Authorized Representative



NEXPERIA B.V.
Name: René Bos
Title: Director

Schedule 1 Transferred Patents

Schedule 1

ReferenceNumber	Status	Title	Region	PriorityDate	FiledDate	ApplicationNumber	PublicationNumber	PatentNumber	Owners
81692179EP01	Application	SEMICONDUCTOR DEVICE	EP	2016-11-21	2016-11-21	16199736.6			NXP B.V.
81891831US01	Application	LEADLESS PACKAGE WITH NON-COLLAPSIBLE BUMP	US	2016-11-03	2016-11-03	15/343172			NXP B.V.
82000269US01	Application	CARRRIER BYPASS FOR Electrostatic discharge	US	2016-11-21	2016-11-21	15/357570			NXP B.V.
82007304US01	Application	LOW RESISTANCE AND LEAKAGE DEVICE	US	2016-11-18	2016-11-18	15/355769			NXP B.V.
82013718US01	Application	SEMICONDUCTOR DEVICE WITH WETTABLE CORNER LEADS	US	2016-11-06	2016-11-06	15/344564			NXP B.V.
82015223US01	Application	METHOD OF MOUNTING PASSIVE ELECTRONIC COMPONENT ON LEAD FRAME	US	2016-12-07	2016-12-07	15/371219			NXP B.V.
82016773US01	Application	SEMICONDUCTOR WAFER DICING METHOD	US	2016-12-15	2016-12-15	15/379495			NXP B.V.
82017660US01	Application	SEMICONDUCTOR DEVICE SND METHOD WITH CLIP ARRANGEMENT IN IC PACKAGE	US	2016-12-19	2016-12-19	15/382805			NXP B.V.
82017660US02	Application	INTEGRATED CIRCUIT (IC) PACKAGE CLIP	US	2016-12-19	2016-12-19	29/588103			NXP B.V.

RECORDED: 02/02/2017

PATENT
REEL: 041162 FRAME: 0612